

ABSTRACT OF THE DISCLOSURE

To provide a semiconductor device capable of corresponding to an applied bending stress by flexibly changing its shape, and to

5 provide a semiconductor device module, a manufacturing method of the semiconductor device, and a manufacturing method of the semiconductor device module. In a silicon substrate whose front surface is provided with an element forming layer having an element forming region where a semiconductor element is formed, a

10 groove is formed in a portion of the rear surface of the silicon substrate corresponding to a region of the element forming layer where a semiconductor element is not formed.